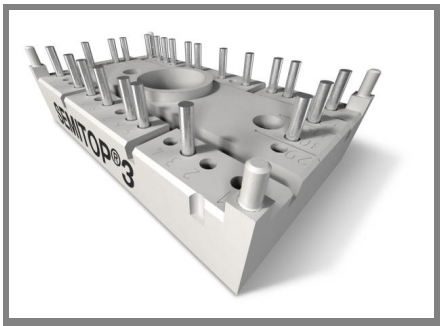
SK 55 DGL 126



SEMITOP® 3

3-phase bridge rectifier + brake chopper

SK 55 DGL 126

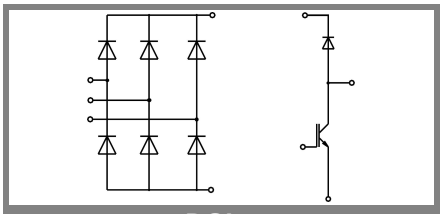
Preliminary Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded alumium oxide ceramic (DCB)
- Trench IGBT technology
- CAL Technology FWD

Typical Applications*

- Rectifier



DGL

Absolute Maximum Ratings		T_s= 25°C, unless otherwise specified	
Symbol	**Conditions**	**Values**	**Units**
IGBT - Chopper			
V_{CES}		1200	V
I_C	T_s = 25 (80) °C	40 (32)	A
I_{CRM}	I_{CRM}= 2 x I_{Cnom}, t_p = 1 ms	70	A
V_{GES}		±20	V
T_j		-40 ... +150	°C
Diode - Chopper			
I_F	T_s = 25 (80) °C	45 (35)	A
I_{FRM}	I_{FRM} = 2xI_{Fnom}, t_p = 1 ms	100	A
T_j		-40 ... +150	°C
Rectifier			
V_{RRM}		1600	V
I_D	T_s = 80 °C	55	A
I_{FSM} / I_{TSM}	t_p = 10 ms , sin 180 ° ,T_j = 25 °C	370	A
I^2t	t_p = 10 ms , sin 180 ° ,T_j = 25 °C	685	A²s
T_j		-40 ... +150	°C
T_{sol}	Terminals, 10s	260	°C
T_{stg}		-40 ... +125	°C
V_{isol}	AC, 1 min. / 1s	2500 / 3000	V

Characteristics		T_s= 25°C, unless otherwise specified			
Symbol	**Conditions**	**min.**	**typ.**	**max.**	**Units**
IGBT - Chopper					
V_{CEsat}	I_C = 35 A, T_j = () °C		1,7 (2)	2,1	V
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 1,5 mA	5	5,8	6,5	V
$V_{CE(TO)}$	T_j = 25 °C (125) °C		1 (0,9)	1,2	V
r_T	T_j = 25 °C (125) °C		20 (31)	26	mΩ
C_{ies}	V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz		2,4		nF
C_{oes}	V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz		0,5		nF
C_{res}	V_{CE} = 25 V_{GE} = 0 V, f = 1 MHz		0,4		nF
$R_{th(j-s)}$	per IGBT			1,05	K/W
$t_{d(on)}$	under following conditions		85		ns
t_r	V_{CC} = 600 V, V_{GE} = ± 15 V		30		ns
$t_{d(off)}$	I_C = 30 A, T_j = °C		430		ns
t_f	R_{Gon} = R_{Goff} = 22 Ω		90		ns
E_{on}	inductive load		4,6		mJ
E_{off}			4,3		mJ
Diode - Chopper					
V_F = V_{EC}	I_F = 45 A, T_j = () °C		1,5 (1,5)	1,77 (1,77)	V
$V_{(TO)}$	T_j = °C (125) °C		(0,92)		V
r_T	T_j = °C (125) °C		(13,4)		mΩ
$R_{th(j-s)}$	per diode			1,2	K/W
I_{RRM}	under following conditions		30		A
Q_{rr}	I_F = 50 A, V_R = 600 V		10		µC
E_{rr}	V_{GE} = 0 V, T_j = °C				mJ
	$di_{F/dt}$ = 500 A/µs				
Diode rectifier					
V_F	I_F = 25 A, T_j = () °C		-	1,25	V
$V_{(TO)}$	T_j = 150 °C		0,8		V
r_T	T_j = 150 °C		13		mΩ
$R_{th(j-s)}$	per diode		2		K/W
Temperatur sensor					
R_{ts}	%, T_r = ( ) °C		()		Ω
Mechanical data					
w			30		g
M_s	Mounting torque			2,5	Nm

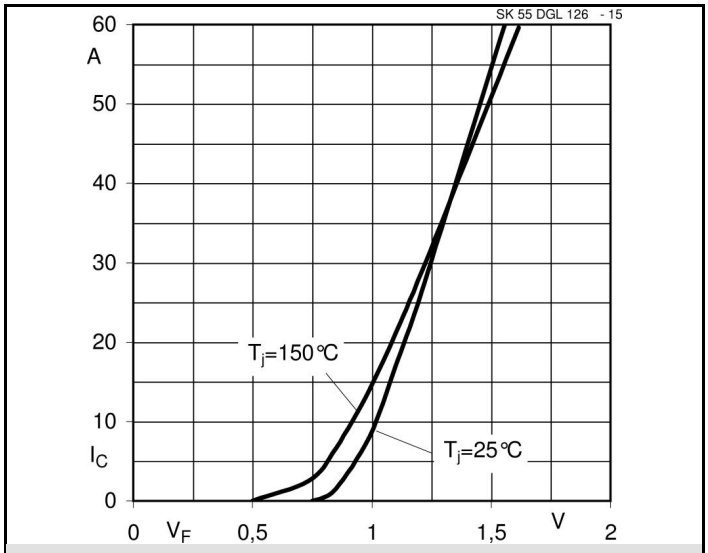


Fig.15 Typical input diode bridge forward characteristic

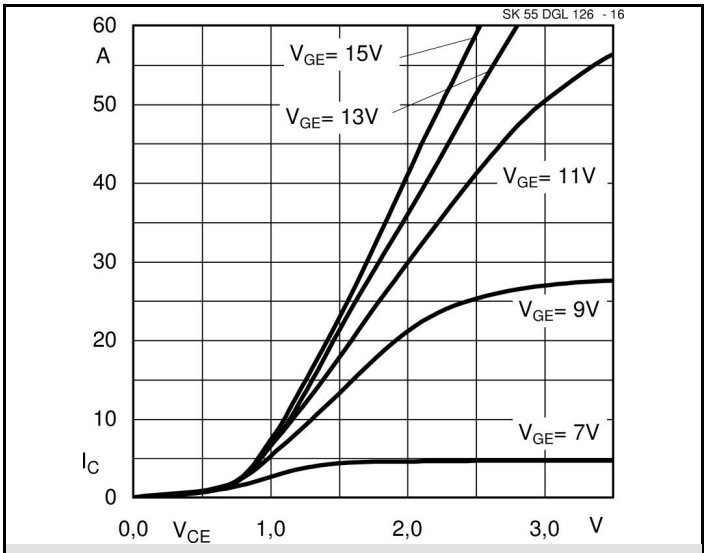


Fig.16 Typical IGBT output characteristic

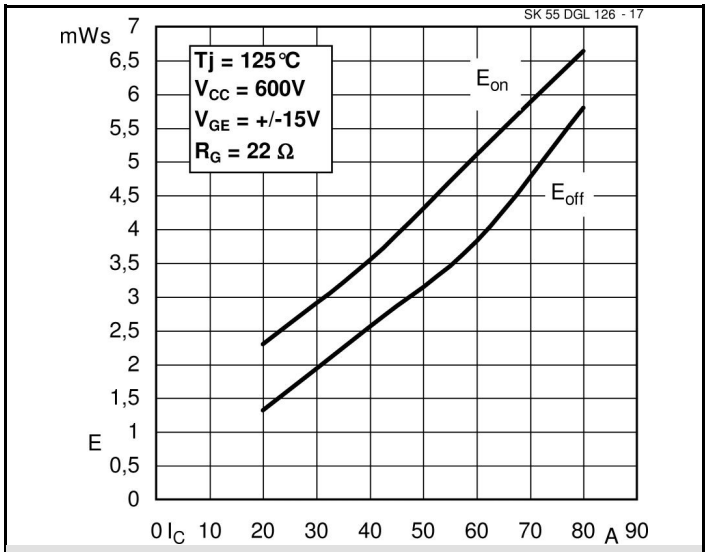


Fig.17 Turn-on/off energy=f(Ic)

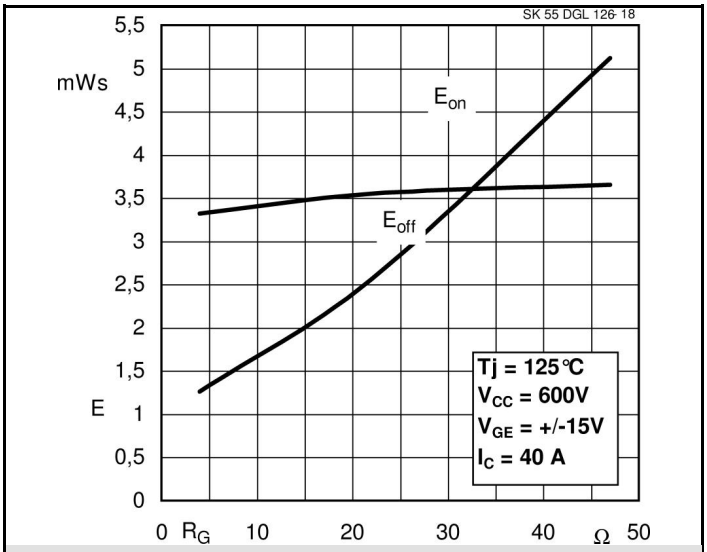


Fig. 18 Turn-on/off energy=f(Rg)

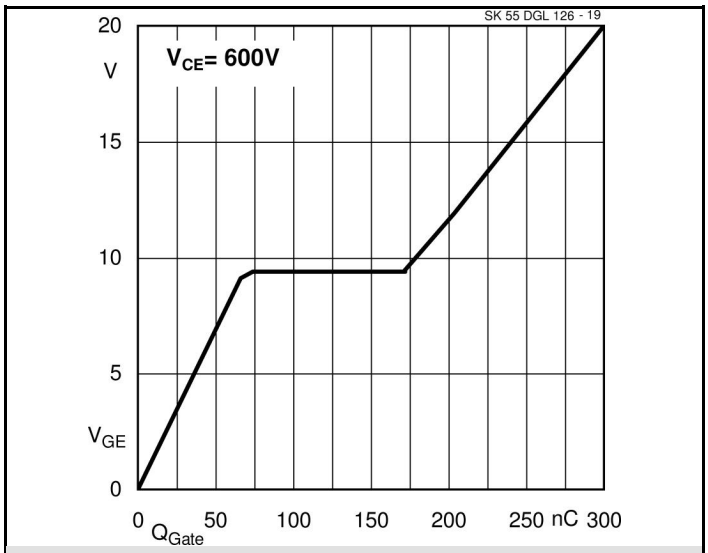


Fig.19 Typical gate charge characteristic

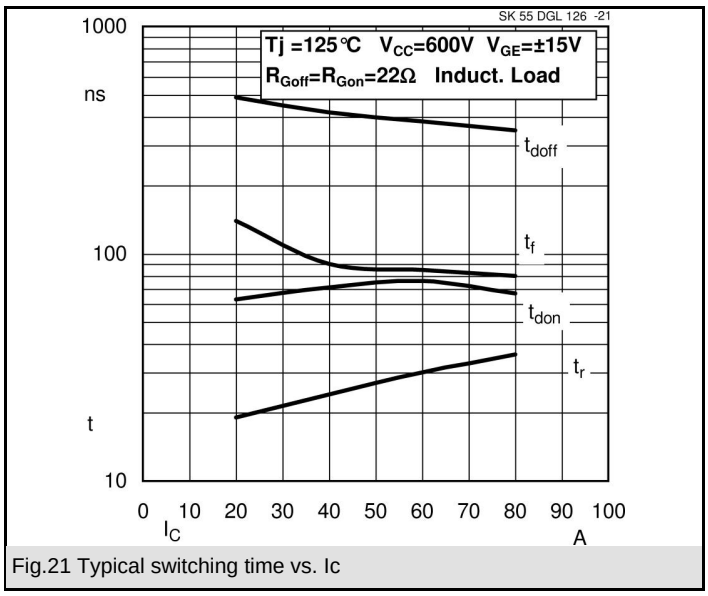


Fig.21 Typical switching time vs. Ic

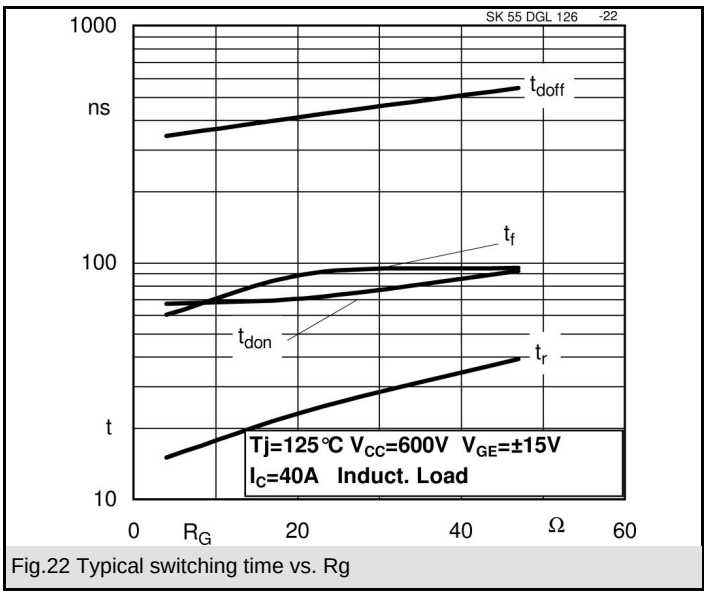
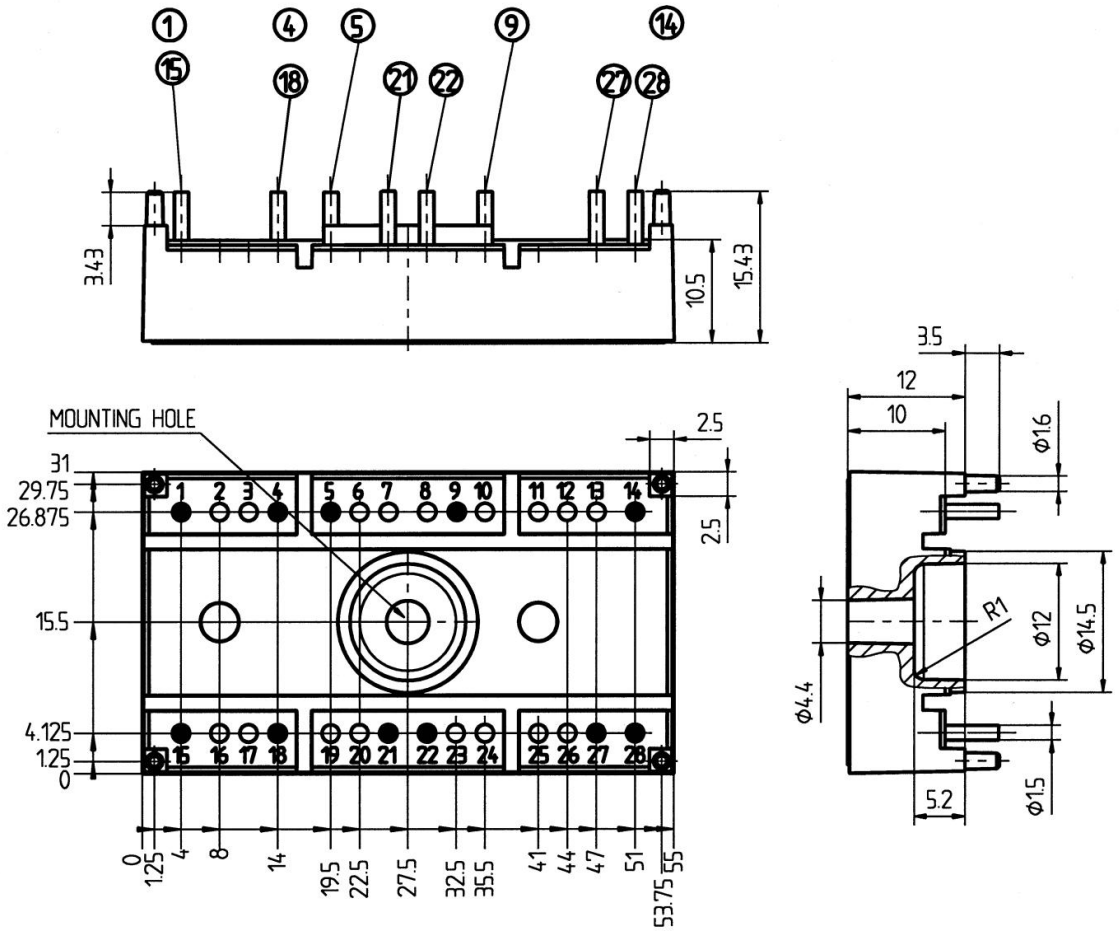
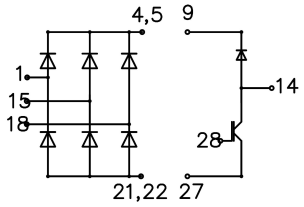


Fig.22 Typical switching time vs. Rg

Dimensions in mm



Case T 14 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)



Case T 14

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

